

TOSHIBA RECTIFIER SILICON DIFFUSED JUNCTION TYPE

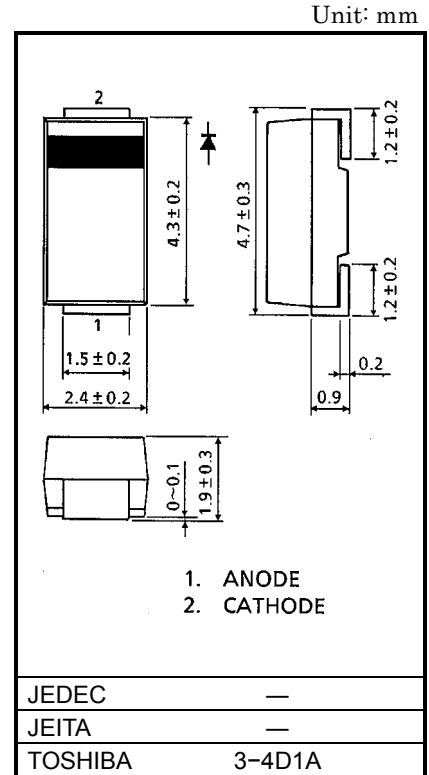
# U1BC44,U1GC44,U1JC44

FOR HYBRID USE

- Average Forward Current :  $I_F (AV) = 1.0A$
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 100, 400, 600V$
- Mini Plastic Mold Package

## MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	U1BC44	$V_{RRM}$	100	V
	U1GC44		400	
	U1JC44		600	
Average Forward Current	On Ceramic Substrate	$I_F (AV)$	1.0 (Ta = 75°C)	A
	On Glass-epoxy Substrate		0.9 (Ta = 25°C)	
Peak One Cycle Surge Forward Current (Non-Repetitive)		$I_{FSM}$	30 (50Hz)	A
			33 (60Hz)	
Junction Temperature		$T_j$	-40~150	°C
Storage Temperature Range		$T_{stg}$	-40~150	°C

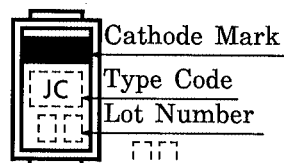
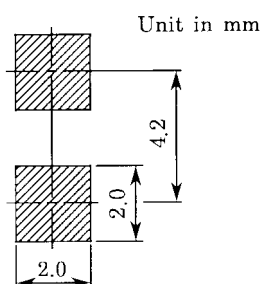


Weight: 0.06g

## ELECTRICAL CHARACTERISTICS (Ta = 25°C)

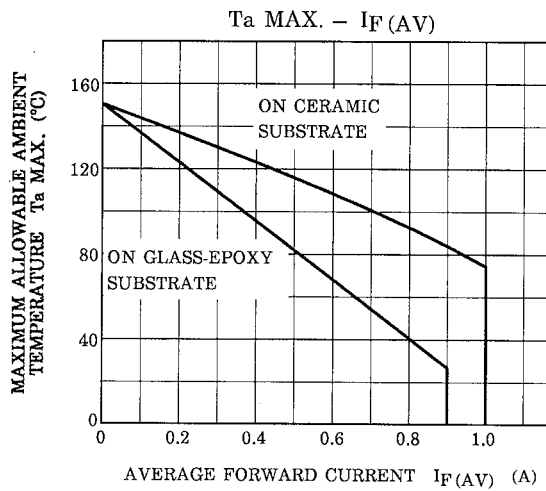
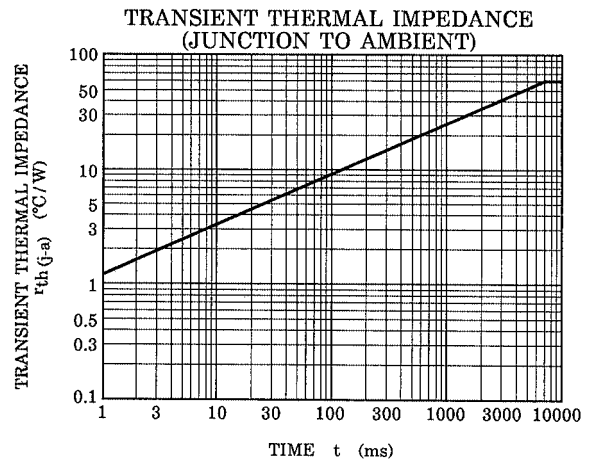
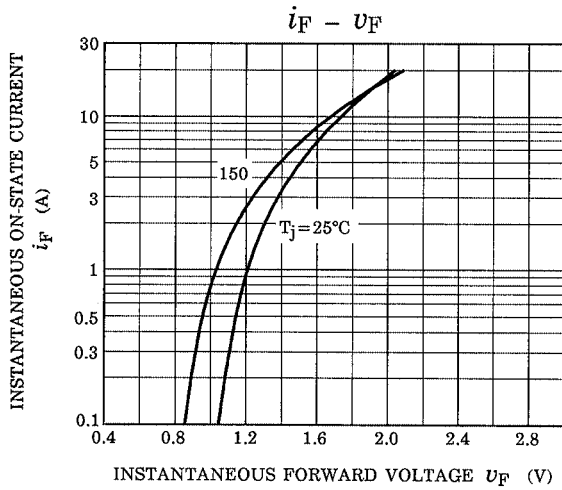
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	$V_{FM}$	$I_{FM} = 1.0A$	—	—	1.2	V
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM} = \text{Rated}$	—	—	10	μA
Thermal Resistance	$R_{th(j-a)}$	DC	—	—	60	°C / W
					On glass-epoxy substrate	

## STANDARD SOLDERING PAD

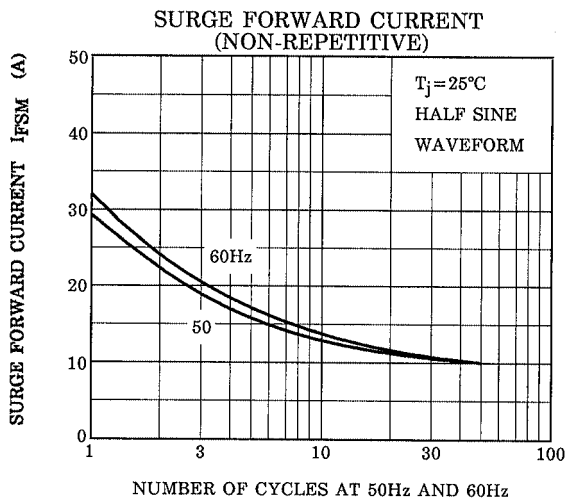


CODE	TYPE
BC	U1BC44
GC	U1GC44
JC	U1JC44

Month (Starting from Alphabet A)  
Year (Last Number of the Christian Era)



	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering land : $a$ □	2mm □	6mm □
Substrate size : $b$ □	50mm □	50mm □
Substrate thickness : $c$ □	0.64t	1.6t



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000707EAA

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